

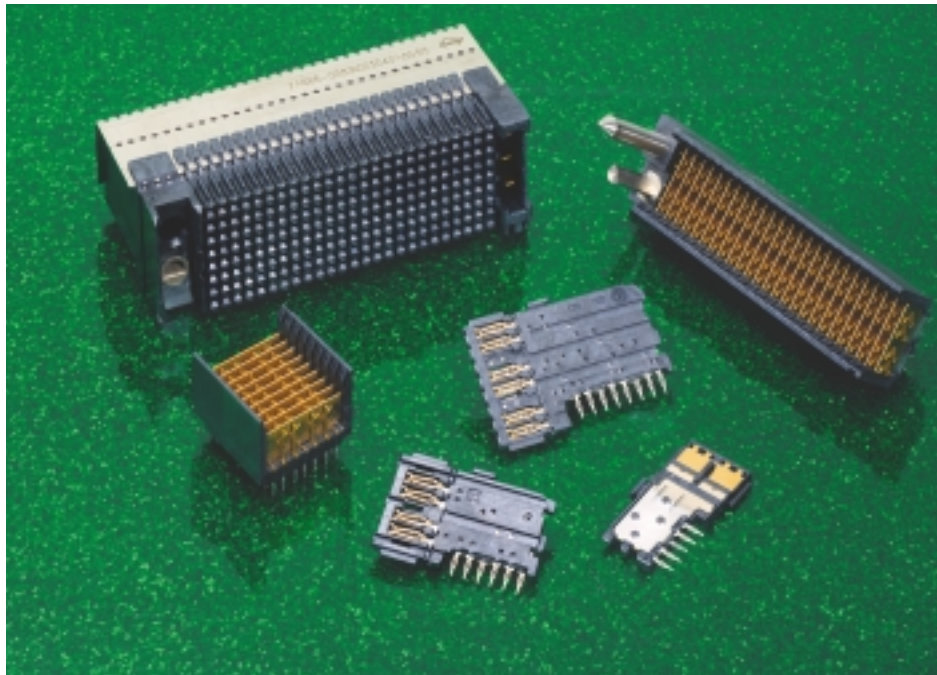
FEATURES AND SPECIFICATIONS

Features and Benefits

- Up to 5.0 Gbps bandwidth per signal pair enables state-of-the-art system design and performance
- 2.00 by 2.25mm (.079 by .089") pitch provides real signal density of 10 differential pairs for 5-row and 6-row and 15 differential pairs for 8-row per centimeter (25 and 38 pairs respectively per inch)
- Minimum distance between daughtercards:
 - 5-row system offers 15.00mm (.591")
 - 6-row system offers 18.00mm (.709")
 - 8-row system offers 22.00mm (.866")
- Ground planes between signal columns provide tightly controlled impedance for rise times down to 50 picoseconds (10-90%). This ensures very low cross talk between signals within and between columns
- Ground pins are in the same grid as signal pins, allowing wider channels for PCB routing and traces up to 0.25mm (.010") wide
- 6-row or 8-row VHDM-HSD wafers can be applied to the same stiffener as standard VHDM® 6-row or 8-row wafers. The combination of VHDM and VHDM-HSD wafers, grouped together in the same stiffener, provides cost effective solutions to different performance parameters



2.00 by 2.25mm (.079 by .089") Pitch 5-Row, 6-Row and 8-Row VHDM-HSD™ Module-to-Backplane Connector System



The Very High Density Metric High Speed Differential (VHDM-HSD) connector system has been expanded to include 5-row, 6-row and 8-row daughtercard and backplane modules. VHDM-HSD is designed for differential-pair architecture applications that require very high interconnect density and signal integrity in a single-ended configuration.

The same great modularity features and components of VHDM are provided in the VHDM-HSD. The 5-row and 6-row systems feature 2 signal pairs per column and the 8-row system features 3 signal pairs per column in increments of 10 and 25 columns. All circuits are utilized as signal circuits without the need to use some as ground circuits.

The daughtercard connector consists of a metal stiffener just as with the VHDM system. The system combines the signal wafers, power modules and guidance modules into one continuous connector that can be ordered as a single specific part number. The card pitch of the VHDM-HSD 8-row system is the same as the standard VHDM 8-row system, allowing both signal wafer types for single ended and differential pair to be used together. This modularity and design flexibility allow engineers to incorporate both connector systems on the same platforms. The system is based on a 2.00mm (.079") pitch and includes vertical and right angle products that can be configured up to 2000 circuits. The maximum length of a daughtercard connector on a single stiffener is 300mm (12").

The backplane connectors feature headers with open ends for continuous side-to-side stacking and headers with guide pins and polarizing keys on either end to aid in proper alignment of the mating daughtercard. The power modules occupy just a small width and hold sequentially matable pins that each manage 10.0 amps of current.

Molex offers application tooling for pressing VHDM-HSD connectors into PCBs as separate modules or as complete assemblies. VHDM-HSD cable assemblies are also available for connecting backplane headers to high-performance cables.

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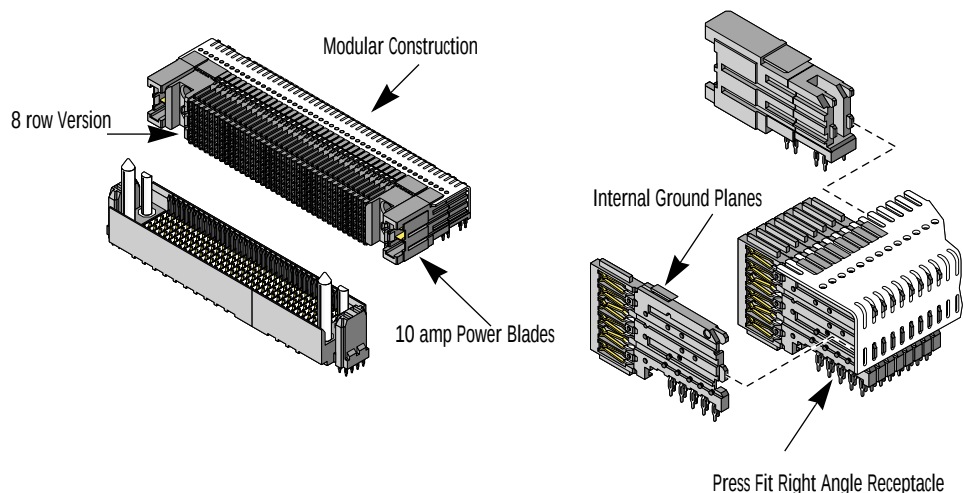
Applications

The VHDM-HSD products are used in very high speed, short rise-time, high circuit count applications connecting daughtercards to the backplane:

- Network Switches
- Routers
- Computer Servers
- Telecommunication Equipment
- Internetworking Devices



2.00 by 2.25mm (.079 by .089") Pitch 5-Row, 6-Row and 8-Row VHDM-HSD™ Module-to-Backplane Connector System



ORDERING INFORMATION

Daughtercard Assembly	Configuration	5-Row	6-Row	8-Row
Signal wafers, power modules and guide modules sequentially assigned by application	VHDM-HSD wafers	74670-XXXX	74880-XXXX	74680-XXXX
	Combination of VHDM and VHDM-HSD wafers	74686-XXXX	74886-XXXX	74686-XXXX

Backplane Header Signal Module Standard Loaded	Pin Height 0.76µm (30µ") Gold	5-Row		6-Row		8-Row	
		10-Column	25-Column	10-Column	25-Column	10-Column	25-Column
Open Ended	4.25mm (.167")	74695-1003	74695-2503	74979-1003	74979-2503	74649-1003	74649-2503
	4.75mm (.187")	74695-1001	74695-2501	74979-1001	74979-2501	74649-1001	74649-2501
	5.15mm (.203")	74695-1004	74695-2504	74979-1004	74979-2504	74649-1004	74649-2504
	6.25mm (.266")	74695-1002	74695-2502	74979-1002	74979-2502	74649-1002	74649-2502
Left Guide Pin No Polarizing Key	4.25mm (.167")	74696-1003	74696-2503	—	—	74650-1003	74650-2503
	4.75mm (.187")	74696-1001	74696-2501	—	—	74650-1001	74650-2501
	5.15mm (.203")	74696-1004	74696-2504	—	—	74650-1004	74650-2504
	6.25mm (.266")	74696-1002	74696-2502	—	—	74650-1002	74650-2502
Left Guide Pin "A" Polarizing Key	4.25mm (.167")	74696-1013	74696-2513	—	—	74650-1013	74650-2513
	4.75mm (.187")	74696-1011	74696-2511	—	—	74650-1011	74650-2511
	5.15mm (.203")	74696-1014	74696-2514	—	—	74650-1014	74650-2514
	6.25mm (.266")	74696-1012	74696-2512	—	—	74650-1012	74650-2512
Right Guide Pin No Polarizing Key	4.25mm (.167")	74697-1003	74697-2503	—	—	74651-1003	74651-2503
	4.75mm (.187")	74697-1001	74697-2501	—	—	74651-1001	74651-2501
	5.15mm (.203")	74697-1004	74697-2504	—	—	74651-1004	74651-2504
	6.25mm (.266")	74697-1002	74697-2502	—	—	74651-1002	74651-2502
Right Guide Pin "A" Polarizing Key	4.25mm (.167")	74697-1013	74697-2513	—	—	74651-1013	74651-2513
	4.75mm (.187")	74697-1011	74697-2511	—	—	74651-1011	74651-2511
	5.15mm (.203")	74697-1014	74697-2514	—	—	74651-1014	74651-2514
	6.25mm (.266")	74697-1012	74697-2512	—	—	74651-1012	74651-2512

Backplane Power and Guide Components	5-Row and 6-Row	8-Row
Power Module	74029-6000	74029-8000
Keying Post	74069-0010	74069-0010
Guide Pin	74076-0001/0002	74076-0001/0002

Note: VHDM and VHDM-HSD are trademarks or registered trademarks of Teradyne, Inc.

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Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
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- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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